English version follows

TestConX中国 China 征稿启事-BiTS/TestConX 中国 2018

BiTS/TestConX 中国 2018 研讨会 (苏州)， 2018 年 10 月 23 日（周二）苏州，中国

BiTS/TestConX 中国 2018 研讨会 (深圳)， 2018 年 10 月 25 日（周四） 深圳，中国

半导体芯片“老化及性能测试技术研讨会”Burn-in and Test Strategies (BiTS) China Workshop 即将拉开帷幕! 我们很荣幸地宣布 2018 年的 BiTS 研讨会更名为 TestConX 中国，并将在苏州、深圳举办两场研讨会，旨在为业内精英提供信息交流平台，期盼各位就与行业相关的主题展开广泛且深入的讨论。

特此 TestConX 组委会诚挚邀请业内优秀人士踊跃来稿！

初稿来稿请提供 250 至 500 字的演讲摘要（内容原创且之前未发表，PPT 演讲材料即可，无需提供文章）、演讲标题、演讲者及作者完整信息（所有作者姓名，工作单位，职务，电子邮箱，电话，邮寄地址），并请注明是否参加两场研讨会或将参加哪场研讨会。截止时间：2018 年 6 月 29 日。

投稿方式：在线投稿（网址 https://bitsworkshop.org/china-abstracts）或发送至电子邮箱（china-abstracts@bitsworkshop.org）。

BiTS China 技术委员会将审阅摘要并在 2018 年 7 月 13 日左右通知投稿者。最终约稿者将在 BiTS China 研讨会上做 30 分钟的展示（25 分钟演讲加 5 分钟问答）。PPT 演讲终稿提交截止时间：2018 年 8 月 31 日。

来稿语言： 英文或中文。

请参考以下报告主题（不局限于此）：

Electrical & Mechanical Challenges in package testing

- Wafer Level Packages (WLP) and Panel Level Processing (PLP)
- Thinner Packages & Package-on-Package (PoP)
- Design tools: geometric dimensioning and tolerancing (GD&T); finite element analysis (FEA), etc.
- Ball deformation & package stress
- Package alignment
- High frequency and high data rate techniques and technologies
- High current, high power, and/or high temperature device testing
- Handler & change kit designs and considerations
- Managing ESD
- Fine Pitch Kelvin Contacting
- Automotive semiconductor requirements
- Thermal management and modelling

- Contact technology: dissimilar metal interface degradation, carbon nanotube developments, non-traditional interface materials, contact reliability in test and burn-in conditions
- Voltage and current extremes, high and low
- PoP, Bare Die, system on a chip (SOC), and 3D package testing
- Wafer level chip scale (WLCSP) test for Known Good Die (KGD) or final test
- Lead-Free
- Minimizing metals & plating of material
- Low power and/or alternative power
- Interconnect solutions for photovoltaic products
- Cradle to cradle manufacturing
- Temperature/Humidity/Bias (THB), highly accelerated stress test (HAST) or other special

Test Process & Operational Challenges

- Test & Burn-in floor operations
- Socket repair, cleaning, and re-plating methods
- Value Engineering: methods and techniques for reducing cost of ownership, achieving low-cost burn-in, etc.
- Massively parallel and non-singulated test
- Test strategies for reducing qualification and production time
- Socket & PCB verification, checkout & qualification
- Strip Testing
- Test-in-Tray
- High reliability testing for mission critical and medical applications
- Microelectromechanical system (MEMS) and non-electrical (optical, fluidic, magnetic, acoustic, etc.) stimuli testing

Module & Product Test Challenges

- Fixturing and test contact
- Test automation
- Automated material handling
- Wireless testing at scale / high volume
- Thermal control

Printed Circuit Board (PCB) Design & Manufacturing Challenges

- For high temperature Burn-in board applications
- High data rate test applications
- Space Transformers
- Ultra-fine pitch
- Board to Board Interconnects
- CTE, force & planarity issues
- Temperature/Humidity/Bias (THB), highly accelerated stress test (HAST) or other special applications

TestConX China 2018

Suzhou – Tuesday October 23, 2018
Shenzhen – Thursday October 25, 2018

The Burn-in and Test Strategies (BiTS) Workshop is pleased to announce due to overwhelming interest there will be two TestConX China Workshops in 2018! On Monday October 22, 2018 the 4th annual China event will be held in Suzhou. And to support the test community in the Guangdon region, the second event will be on Thursday October 25, 2018 in Shenzhen. *Don't miss the two preeminent China events focused on connecting electronic test professionals to solutions.*

The TestConx Technical Program Committee is seeking presentation proposals on a broad range of test and burn-in topics.

Each presentation at TestConX China is provided a thirty minute presentation slot (approximately 25 minutes for the presentation with 5 minutes for questions and answers). Authors may choose to present at both TestConX China events or just one as fits their schedule. And authors only need to prepare a PowerPoint presentation. (There is no paper to write.)

Please submit a 250 to 500 word abstract for presentations or posters of your original, previously unpublished, technical presentation by June 29, 2018.

Submit via:

- Online form https://bitsworkshop.org/china-abstracts

or

- Email china-abstracts@bitsworkshop.org including title of presentation, complete contact information (name, affiliation/company name, job title, email address, phone number, and mailing address) for each author, and name of presenter. Be sure to indicate availability to present at one (Suzhou or Shenzhen) or both events.

Abstracts will be reviewed and authors will be notified around July 13, 2018.

Presentations submissions are due August 31, 2018.

Language: English or Mandarin

Topics of interest include, but are not limited to:

Electrical & Mechanical Challenges in package testing

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